

1

Typical applications

- AC and DC electric motor control;
- Frequency transformer;
- UPS;
- Industry power supply;
- Electric welding machine.

Characteristic

- SPT chip (soft-punch-through)
- MOS input control
- Ultra thin IGBT chip, great current low loss, low tail current
- Low VCE (sat) saturated voltage, positive temperature coefficient at high temperature
- High switch frequency, low switch loss
- High SC resistive ability
- Module creepage long distance design
- DBC insulated voltage above 2500VRMS



G75-12CS1 Technical Details

Maximum rated values

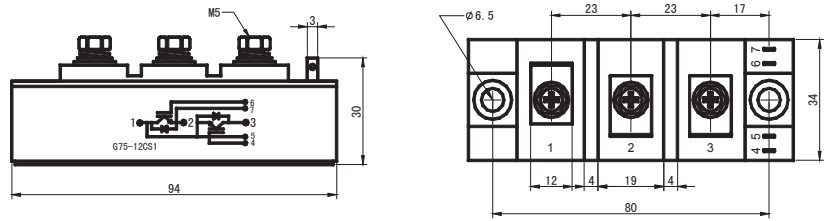
Absolute Max. Ratings			Tc=25°C unless specified	
Name	Symbol	Conditions	values	Unit
IGBT				
Collector-emitter voltage	V _{CES}		1200	V
DC-collector current	I _C	T _c =25(80)°C	100(75)	A
repetitive peak voltage	I _{CRM}	T _c =25(80)°C, tp=1ms	200(150)	A
gate-emitter peak voltage	V _{GES}		±20	V
operation temperature	T _{vj}		-40~+125	°C
storage temperature	T _{stg}		-40~+150	°C
insulation test voltage	V _{ISOL}	RMS, 1min, 50Hz	2500	V
Inverse diode				
DC-forward current	I _F	T _c =25(80)°C	100 (75)	A
repetitive peak forward voltage	I _{FRM}	T _c =25(80)°C, tp=1ms	200 (150)	A
forward surge current	I _{FSM}	tp=10ms, sin, T _j =125°C	700	A

Characteristic values

Absolute Max. Ratings			Tc=25°C unless specified			IGBT
Paramiter	Symbol	Conditions	values			
			min.	typ.	max.	
IGBT						
gate threshold voltage	V _{GE(th)}	V _{GE} =V _{CE} , I _c =2mA, T _j =25°C	5		7	V
collector-emitter cut-off current	I _{CES}	V _{GE} =0V, V _{CE} =V _{CES}		0.1	0.3	mA
gate-leakage current	I _{GES}	V _{GE} =0V, V _{GE} =±20V, T _j =25°C	-200		200	nA
collector-emitter threshold voltage	V _{CE (TO)}	T _j =25 (125)°C		1(0.9)	1.15(1.05)	V
collector-emitter slope resistance	r _{CE}	V _{GE} =15V, T _j =25 (125)°C	13(16)		16(20)	mΩ
collector-emitter saturation vorage	V _{CE(SAT)}	I _c =75 A, V _{GE} =15V, chip level	1.9 (2.1)		2.35 (2.55)	V
input capacitance	C _{ies}			6.2		nF
output capacitance	C _{oes}	V _{GE} =0, V _{CE} =25V, f=1MHZ		0.74		nF
Reverse transfer capacitance	C _{res}			0.71		nF
stray inductance module	L _{CE}				25	nH
module lead resistance	R _{CC'+EE'}	terminals-chip, T _c =25 (125)°C	0.75 (1)			mΩ
Short circuit current	I _{sc}	tpsc≤10s, V _{GE} =15V, T _{vj} =125°C, V _{CC} =900V, V _{CEM} ≤1200V	420			A
turen on delay time	t _{d (on)}	V _{CC} =600V, I _c =75A R _{gon} =R _{goff} =12Ω T _j =125°C, V _{GE} =±15V	150			ns
rise time	t _r		45			ns
turn off delay time	t _{d (off)}		560			ns
fall time	t _f		50			ns
turn-on energy loss per pules	E _{on}		8.5			mj
turn-off energy loss per pulse	E _{off}		7.5			mj
Inverse diode						
forward voltage	V _F	I _F =75A, V _{GE} =0V; T _j =25(125)°C		2(1.8)	2.5(1.9)	V
threshold voltage of diode	V _(TO)	T _j =25(125)°C		1.1	1.2	V
peak reverse recovery current	I _{RRM}	I _F =75A, V _{GE} =0, diF/dt=600A/us,	62			A
Reverse recovered time	t _{rr}	T _j =125, V _R =600V	200			nS
Thermal properties						
Thermal resistance, junction to case	R _{th(j-c)}	per IGBT	0.2			K/W
	R _{th(j-c)D}	per inverse diode	0.5			K/W
Thermal resistance, case to heat sink	R _{th(c-s)}	per module	0.05			K/W
Mechanical properties						
mounting torque	M1	M6	3		5	NM
terminal connection tord	M2	M5	2.5		5	NM
weight	MAX	176				g
Case color		white				
Dimensions	MAX	94x34x30.5				mm

G75-12CS1 Technical Details

Dimensions



Graphs

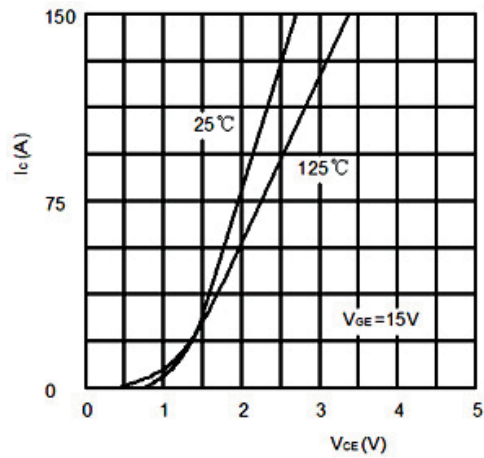


Fig. 1 Typ. output characteristic

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